

Integrated Device Technology, Inc. 6024 Silver Creek Valley Road, San Jose, CA - 95138

# PRODUCT/PROCESS CHANGE NOTICE (PCN)

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|---|--|---|------------------------------------|-----------------------|
| PCN #: <b>A1602-02</b> Product Affected: FCBGA-1  |  | ☐ Product Mark  | INGUISHING CHAN                    | NGED DEVICES:         |
| Refer to Attachment   | I for the affected part numbers  | ■ Back Mark □ Date Code □ Other   | Lot # will have: "R" prefix for AS | EK, Taiwan            |
| Date Effective: 18-Aug-201  | 6  |   |                                    |                       |
| Contact: IDT PCN DE   | SK   | Attachment:   | Yes                                | □ No                  |
| E-mail: pcndesk@id  | t.com  |   | contact your local sale request.   | es representative for |
| DESCRIPTION AND PURPO   | SE OF CHANGE:  |   |                                    |                       |
| <ul> <li>□ Die Technology</li> <li>□ Wafer Fabrication Process</li> <li>□ Assembly Process</li> <li>□ Equipment</li> <li>□ Material</li> <li>□ Testing</li> </ul> | This notification is to adviss alternate assembly facility facilit | or parts that are curr  | rently assembled at Ar             |                       |
| ■ Manufacturing Site □ Data Sheet □ Other   |  | Attachment I details the qualification results and Attachment II shows the affected list of part numbers. |                                    |                       |
| <b>RELIABILITY/QUALIFICA</b> Refer to qualification data show   |  |   |                                    |                       |
| to grant approval or request add<br>it will be assumed that this char   | equire written notification of this ch<br>litional information. If IDT does no<br>age is acceptable.<br>ther version manufactured after the  | t receive acknowled   | gement within 30 days              | s of this notice      |
| Customer:   |  | ] Approval for  | r shipments prior                  | to effective date.    |
| Name/Date:  |  | -Mail Address:  |                                    |                       |
| Title:  | P  | hone# /Fax# :   |                                    | _                     |
| CUSTOMER COMMENTS:  |  |   |                                    |                       |
|   |  |   |                                    |                       |
| IDT ACKNOWLEDGMENT  | OF RECEIPT:  |   |                                    | _                     |
|   |  | DATE:   |                                    | _                     |

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### **ATTACHMENT I - PCN # : A1602-02**

**PCN Type:** Manufacturing Site - Alternate Assembly Location

**Data Sheet Change:** None

No change in moisture sensitivity level (MSL)

#### **Detail Of Change:**

This notification is to advise our customers that IDT is adding ASEK, Taiwan as an alternate assembly facility for parts that are currently assembled at Amkor Philippines and Amkor Taiwan.

The material set details of the current and alternate assembly location is as shown in Table 1.

There is no change to the moisture performance.

Table 1: Assembly Material Sets for The Existing and Alternate Assembly Location

|                             | Existing:<br>Amkor Philippines | Existing:<br>Amkor Taiwan     | Alternate:<br>ASEK Taiwan     |
|-----------------------------|--------------------------------|-------------------------------|-------------------------------|
| Heat spreader thermo grease | DCL-5                          | SHA-1                         | SE4450                        |
| Adhesive                    | DCL-5                          | DCL-4                         | SE4450                        |
| Die bump                    | Sn1.8Ag                        | Sn1.8Ag                       | Sn1.8Ag                       |
| Underfill                   | NAU-27                         | NAU27                         | UA32                          |
| Substrate                   | ABF-GX13/<br>E679 Core         | ABF-GX13/<br>E679 Core        | ABF-GX13/<br>E679 Core        |
| Solder balls                | Sn96.5/Ag3.0/Cu0.5<br>(Green)  | Sn96.5/Ag3.0/Cu0.5<br>(Green) | Sn96.5/Ag3.0/Cu0.5<br>(Green) |

## PRODUCT/PROCESS CHANGE NOTICE (PCN)

### **ATTACHMENT I - PCN # : A1602-02**

### **Qualification Information and Qualification Data:**

**Affected Packages:** FCBGA-1156

**Assembly Material:** Shown on page 2 of this attachment.

**Qual Plan & Results:** Tests are in accordance with JEDEC47 recommended tests.

**Qualification Vehicle:** FCBGA-1156

| Toot Description                                   | Test Method  | Test Results (Rej / SS) |       |       |
|--|--------------|-------------------------|-------|-------|
| Test Description                                   | Test Wiethou | Lot 1                   | Lot 2 | Lot 3 |
| * Temperature Cycling (-55°C to 125°C, 700 cycles) | JESD22-A104  | 0/25                    | 0/25  | 0/25  |
| * HAST - unbiased<br>(130 °C/85% RH, 96 Hrs)       | JESD22-A118  | 0/25                    | 0/25  | 0/25  |
| High Temperature Storage Bake (150°C, 1000 Hrs)    | JESD22-A103  | 0/25                    | 0/25  | 0/25  |

<sup>\*</sup> Tests were subjected to Preconditioning per JESD22-A113 prior to stress test

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## ATTACHMENT II - PCN #: A1602-02

#### **Affected Part Numbers**

| Part Number       | Part Number       | Part Number      | Part Number      |
|-------------------|-------------------|------------------|------------------|
| 89H22H16G2ZCBLG   | 89H64H16AG2ZCBLG  | 89H48H12AG2ZCBLG | 89H22H16G2ZCBLGI |
| 89H64H16G2ZCBLG   | 89H48H12BG2ZCBLG  | 89H34H16G2ZCBLGI | 89H64H16G2ZCBLGI |
| 89H64H16AG2ZCBLGI | 89H48H12AG2ZCBLGI | 89H34H16G2ZCBLG  |                  |